MAINTENANCE MANUAL

406-512 MHz EXCITER BOARD 19D423346G1-G2 & 19D432582G1-G2

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DESCRIPTION

The exciter uses eight transistors, a crystal module and an integrated circuit to provide 200 milliwatts of RF drive to the PA assembly. The crystal module determines the (F1) transmitting frequency in single frequency applications. The exciter also contains the voltage compensation circuits and provides temperature compensation voltage to all crystal modules.

In multi-frequency transmitters, the crystal modules for frequencies F2-F4 are located on the multi-frequency board. In station applications requiring a frequency stability of 0.0002%, Integrated Circuit Oscillator Modules (ICOMs) are used. All ICOMs (F1-F4) are located on the multi-frequency board. In these applications the F1 oscillator (Q181) on the exciter board is not used.

The crystal frequency ranges from approximately 11.3 to 14.2 megahertz, and is multiplied 36 times.

Audio, supply voltages and control functions are connected from the system-audio & squelch board (SAS) to the exciter board through P902.

Centralized metering jack J103 is used with GE Test Set Model 4EX3All or Test Kit 4EX8K12. The Test Set meters the frequency multipliers, amplifier and measures the relative power out.

CIRCUIT ANALYSIS

F1 OSCILLATOR CIRCUIT

A Colpitts oscillator comprised of Q181, a plug-in crystal module and associated components provides the fundamental operating $\frac{1}{2} \frac{1}{2} \frac{1}$

frequency for the transmitter. The crystal module in the base circuit of Q181 is temperature compensated to maintain frequency stability within ± 5 PPM over a ambient temperature range of $-30\,^{\circ}\mathrm{C}$ to $+60\,^{\circ}\mathrm{C}$. Compensation voltage from compensator circuit Q182 is applied to the crystal module. The output of the oscillator is taken from the collector of Q181 and applied to the input of buffer Q101.

- SERVICE NOTE -

Y1 and C2 on the crystal modules are not field replaceable items. C2 is factory selected to compliment the temperature/frequency characteristics of each individual crystal. Should it become necessary to replace either Y1 or C2, the entire crystal module must be replaced.

In single frequency radios, the F1 keying lead is connected directly to A- by a DA jumper connected between H12 and H31 on the SAS board. This assures F1 oscillator operation each time the PTT switch is pressed.

With the radio turned on and the PTT switch operated, +10 Volts is present on the transmitter oscillator lead at P902-1 and the emitter of Q181. R182 and R183 comprise a voltage divider network to establish the base voltage for Q181, allowing it to oscillate at the crystal frequency to allow F1 frequency selection via the frequency selector switch on the control unit.

When frequencies F2 thru F4 are selected the oscillator output frequency from the multi-frequency board is supplied to buffer Q101 through J102-1 on the exciter and cable W2601.

COMPENSATOR CIRCUITS

The crystal modules are temperature compensated at both ends of the temperature



range to provide instant frequency compensation. The temperature compensator consists of Q182, VR101, RT181, RT192 and associated components. Zener diode VR101 provides a constant +8.5 V reference voltage for compensator Q101.

The cold end compensation circuit does not operate at temperatures above $-10\,^{\circ}\mathrm{C}$ (+14 $^{\circ}\mathrm{F}$). When the temperature drops below $-10\,^{\circ}\mathrm{C}$, the circuit is activated. As the temperature decreases, the resistance of RT181 increases and the compensation voltage increases.

An increase in compensation voltage decreases the capacitance of the varactor in the oscillator, thereby increasing the output frequency of the crystal module.

The hot end compensation circuit does not operate at temperatures below 50°C (122°F). When the temperature rises above +50°C, the circuit is activated. As the temperature increases, the resistance of RT192 decreases and the compensation voltage decreases. The decrease in compensation voltage increases the capacity of the varactor, decreasing the output frequency of the crystal module.

Listed below are typical minimum and maximum voltage readings to be expected at pin 4 of the crystal modules. Voltages should be measured using a high impedance meter.

TEMPERATURE	OUTPUT VOLTAGE		
RANGE	MINIMUM	MAXIMUM	
-30°C -10° to 50°C +75°C	4.9 Volts 3.7 Volts 3.3 Volts	6.0 Volts 4.3 Volts 3.8 Volts	

AUDIO IC

The transmitter audio circuitry is contained in audio IC U101. A simplified drawing of the audio IC is shown in Figure 1.

Audio from the microphone at pin 12 is coupled through pre-emphasis capacitor C1 to the base of Q1 in the operational amplifier-limiter circuit. Collector voltage for the transistorized microphone preamplifier is supplied from the 10-Volt regulator through R980 & R979 on the System-Audio-Squelch board to J901A-14 in MASTR Executive II radios.

In Custom MVP radios, collector voltage for the transistorized microphone preamplifier is supplied from the 20-Volt regulator on the SAS board through R928, R929 and J913 to the microphone.

The operational amplifier-limiter circuit consists of Q1, Q2 and Q3. Q3 provides limiting at high signal levels. The gain of the operational amplifier circuit is fixed by negative feedback through R19, R20 and the resistance in the network (Pin 9).

The output of Q3 is coupled through a de-emphasis network (R10 and C3) to an active post-limiter filter consisting of C4, C5, C6, R11, R12, R13, R15, R17 and Q4.

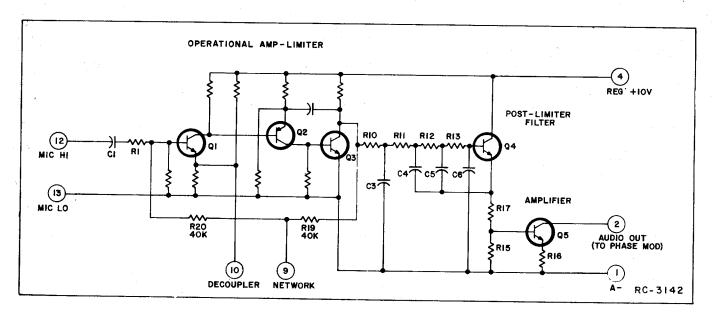


Figure 1 - Simplified Audio IC

Following the post-limiter filter is class A amplifier Q5. The output of Q5 is coupled through MOD ADJUST potentiometer R104 and resistor R109 to the phase modulator.

- SERVICE NOTE .

If the DC voltages applied to the audio IC are correct and there is no audio output, replace UlO1. For radios equipped with Channel Guard, tone from the encoder is applied to the phase modulator through P902-9, (CG H1) and resistor R113. Refer to the Transmitter Alignment procedures for Channel Guard modulation adjustment instructions.

BUFFER & PHASE MODULATOR

The oscillator output present at J102-1 (FL-F4) is coupled through buffer-amplifier Q101 to the modulator. The phase modulator, varactor (voltage-variable capacitor) CR180, is connected in series with tunable coil T101. This network appears as a series-resonant circuit to the RF output of the oscillator. An audio signal applied to the modulator circuit through blocking capacitor C109 varies the bias of CR180, resulting in a phase modulated output. A voltage divider network (R106 and R112) provides the proper operating bias for CR180.

The output of the modulator is coupled through blocking capacitor Cl16 to the base of buffer Q102. Cl16 and Cl17 also provide impedance matching between the modulator and buffer Q102.

MULTIPLIERS & AMPLIFIER

Buffer Q102 is saturated when no RF signal is present. Applying an RF signal to Q102 provides a sawtooth waveform at its

collector to drive class C tripler, Q103. The first tripler stage is metered through R117. The output of Q103 is coupled through tuned circuits T102, T103 and T104 to the base of the second tripler, Q104. T102, T103 and T104 are tuned to three times the crystal frequency. The second tripler stage, Q104, is metered through R122.

The output of Q104 is coupled through tuned circuits T105 and T106 to the base of first doubler Q105. T105 and T106 are tuned to nine times the crystal frequency. Q105 is metered through R126.

The output of Q105 is coupled through two tuned circuits (T107 and T108) to the base of second doubler Q106. These circuits are tuned to 18 times the crystal frequency (one-half the transmitter operating frequency). Q106 is metered through R133.

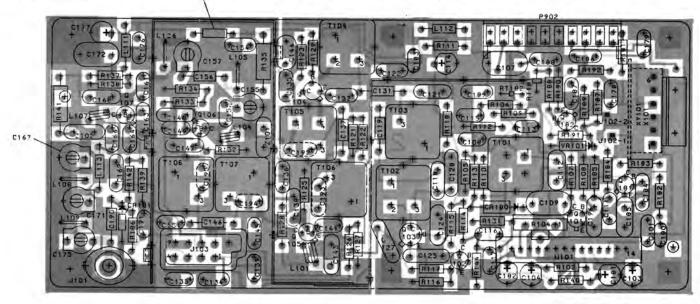
The output of Q106 is coupled to the base of power amplifier Q107 through impedance matching networks composed of C152. C155, L105, C156, C157, L106, and C161. These networks are all tuned to the operating frequency and present a high shunt impedance at the operating frequency. All other frequencies are shunted to ground. Q107 is metered through R142.

The output of Q107 is matched to 50 ohms by impedance matching network C166, C167, L108, L117, C171, L109 and C175. C167, C171, and C175 are tuned to the proper resonant frequency.

The exciter provides a minimum of 200 milliwatts of RF power to the power amplifier through J101 and cable W216. The relative output power of the exciter is metered by coupling through C190, detecting with CR181, and filtering with R186 and C191.

GENERAL ELECTRIC COMPANY+ MOBILE COMMUNICATIONS DIVISION WORLD HEADQUARTERS+LYNCHBURG, VIRGINIA 24502 U.S.A.





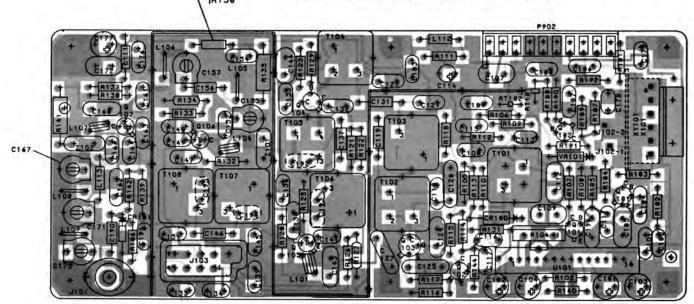
L114 R136

> (19C327178, Rev. 7) (19B232260, Sh. 1, Rev. 4) (19B232260, Sh. 2, Rev. 2)

RUNS ON BOTH SIDES

RUNS ON COMPONENT SIDE

EXCITER BOARD 19D432582G1 & G2

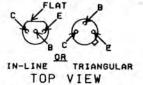


(19D432584, Rev. 1) (19A143645, Sh. 1, Rev. 1) (19A143645, Sh. 2, Rev. 1)

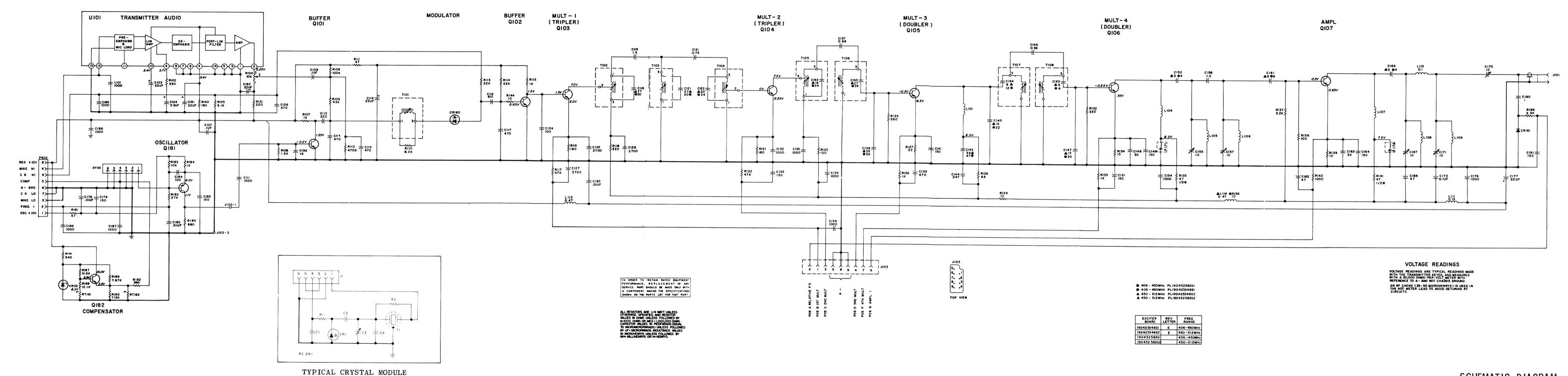
OUTLINE DIAGRAMS

406-512 MHz EXCITER BOARDS

LEAD IDENTIFICATION FOR 0101-0107,0181,8 0182



NOTE: LEAD ARRANGEMENT, AND NOT CASE SHAPE, IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.



(19R622183, Rev. 11)

SCHEMATIC DIAGRAM

406—512 MHz EXCITER BOARD 19D423346G1-G2 & 19D432582G1-G2

Issue 6

LB130088G 406-512 MHz EXCITER BOARD

19D423346G1 406-450 MHz 19D423346G2 450-512 MHz SYMBOL GE PART NO DESCRIPTION Ceramic disc: 1000 pF $\pm 20\%$, 1000 VDCW; sim to RMC Type JF Discap. C101 19A116655P19 Tantalum: 22 uF ±20%, 15 VDCW. C103 L9A134202P6 Tantalum: 3.3 uF +20%. 15 VDCW C104 194134202P5 Polyester: 0.1 uF ±20%, 50 VDCW. C107 19A116080P7 Ceramic disc: 470 pF +20%, 1000 VDCW; sim to RMC C108 19A116655P13 C109 19A116080P10 Polyester: 0.1 uF +10%, 50 VDCW. Ceramic disc: 1000 pF ±20%, 1000 VDCW; sim to C111 194116655P1 19A700105P44 Mica: 220 pF ±5%, 500 VDCW. C112 C113 5496372P365 Ceramic disc: 470 pF +10%, 500 VDCW, temp coef C156* C114 19A134202P6 Tantalum: 22 uF +20%, 15 VDCW. eramic disc: 470 pF ±20%, 1000 VDCW; sim to RMC C115 19A116655P1 Ceramic disc: 910 pF ±10%, 500 VDCW, temp coef C116 5496372P379 C157 C117 5496372P365 Ceramic disc: 470 pF ±10%, 500 VDCW, temp coef Ceramic disc: 30 pF ±5%, 500 VDCW, temp coef -80 C118L 19A116656P30 Ceramic disc: 27 pF ±5%, 500 VDCW, temp coef -80 C162 C118H C119 19A700013P15 Phenolic: 1.50 pF +5%, 500 VDCW. C121L 19A116656P30 Ceramic disc: 30 pF ±5%, 500 VDCW, temp coef -8 C164 19A116656P27.I8 C121H Ceramic disc: 27 pF ±5%, 500 VDCW, temp coef -8 Ceramic disc: 24 pF ±5%, 500 VDCW, temp coef C122L 194116656P24J8 C122H Ceramic disc: 20 pF ±5%, 500 VDCW, temp coef -С166Н C124 19A700105P34 Mica: 100 pF +5%, 500 VDCW. C167 C125 ramic disc: 2700 pF ±20%, 1000 VDCW; sim to 19A116655P21 C168 RMC Type JR Discap. 19A116655P21 Ceramic disc: 2700 pF ±20%, 1000 VDCW; sim to C171 C172 C131 5491601P118 Phenolic: 0.75 pF +5%, 500 VDCW. C175 19A116655P19 ramic disc: 1000 pF ±20%, 1000 VDCW; sim to C132 C176 RMC Type JF Discap. C133 19A116655P7 Ceramic disc: 150 pF $\pm 20\%$, 1000 VDCW; sim to RMC C177 C178 Ceramic disc: 1000 pF ±20%, 1000 VDCW; sim to 19A116655P19 RMC Type JF Discap. C179 C137 19A700013P11 Phenolic: 0.68 pF ±5%, 500 VDCW. C180 C138L 19A116656P56J8 Ceramic disc: 56 pF ±5%, 500 VDCW, temp coef -8 C138H Ceramic disc: 39 pF ±5%, 500 VDCW, temp coef 19A116656P3 Ceramic disc: 470 pF ±20%, 1000 VDCW; sim to RMC C139 19A116655P1 C184 Ceramic disc: 150 pF +20%, 1000 VDCW; sim to RMC C141 19A116655P7 C185 C143L Mica: 47 pF +5%, 500 VDCW. 19A700105P26

DESCRIPTION GE PART NO. SYMBOL Mica: 39 pF ±5%, 500 VDCW. 194700105P23 C143H olvester: 0.047 uF +10%, 50 VDCW. C144 Ceramic disc: 22 pF ±5%, 500 VDCW, temp coef C145L 19A116656P22J C145H 9A116656P15 Ceramic disc: 15 pF ±5%, 500 VDCW, temp coef -194700013P10 Phenolic: 0.56 nF +5%, 500 VDCW. C147L 19A116656P30J8 Ceramic disc: 30 pF ±5%, 500 VDCW, temp coef -80 C147H 19A116656P15J8 Ceramic disc: 15 pF +5%, 500 VDCW, temp coef -8 Ceramic disc: 30 pF ±5%, 500 VDCW, temp coef -C148 9A116656P30J eramic disc: 150 pF $\pm 20\%$, 1000 VDCW; sim to RMC C149 19A116655P7 eramic disc: 150 pF +20%, 1000 VDCW; sim to RMC C151 19A116655P7 Ceramic disc: 4 pF ±0.5 pF, 500 VDCW, temp coef C152L 19A116656P4J C152H eramic disc: 3 pF ±0.5 pF, 500 VDCW, temp coef C153* 19A134666P2 Silver mica: 22 pF +5%, 500 VDCW; sim to Elect Motive Type DM154CR. Deleted by REV E. C154 19A116655P19 Ceramic disc: 1000 pF ±20%, 1000 VDCW; sim to RMC Type JF Discap. 19A700008P1 Variable: 2.04 to 9.9 pF, 250V peak.

Phenolic: 1.20 pF +5%, 500 VDCW.

Phenolic: 1.0 pF ±5%, 500 VDCW.

Variable: 2.04 to 9.9 pF, 250V peak.

Ceramic disc: 6 pF ±5%, 500 VDCW; temp. coef -80

Ceramic disc: 5 pF +5%, 500 VDCW; temp. coef -80

Ceramic disc: 47 pF $\pm 5\%$, 500 VDCW; temp. coef

Ceramic disc: 30 pF ±5%, 500 VDCW, temp coef -80

Ceramic disc: 150 pF +20%, 1000 VDCW; sim to RMC

Silver mica: 18 pF ±5%, 500 VDCW; sim to Electro Motive Type DM154CR. Deleted by REV E.

Ceramic disc: 4 pF ±0.5 pF, 500 VDCW, temp coef

Ceramic disc: 3 pF ±0.5 pF, 500 VDCW, temp coef

Ceramic disc: 47 pF ±5%, 500 VDCW; temp. coef

Ceramic disc: 1000 pF ±20%, 1000 VDCW; sim to

Ceramic disc: 150 pF <u>+</u>20%, 1000 VDCW; sim to RMC Type JF Discap.

Ceramic disc: 100 pF ±5%, 500 VDCW, temp coef -750 PPM.

Variable: 2.04 to 9.9 pF, 250V peak.

Variable: 2.04 to 9.9 pF, 250V peak.

Variable: 2.04 to 9.9 pF, 250V peak.

Polvester: 0.1 uF +10%, 50 VDCW.

Tantalum: 22 uF +20%, 15 VDCW.

Polyester: 0.01 uF ±10%, 50 VDCW.

Polyester: 0.01 uF ±10%, 50 VDCW.

Polvester: 0.01 uF +10%, 50 VDCW.

Tantalum: 22 uF ±20%, 15 VDCW.

Mica: 150 pF ±5%, 500 VDCW.

RMC Type JF Discap.

In REV B & earlier:

19A700013P14

5491601P120

19A700008P1

19A116656P5J8

19A116656P47J

19A116656P30J

19A116655P7

19A134666P1

19A116656P4J

19A116656P3J

19A700008P1

19A116656P47

19A700008P1

19A116080P10

19A700008P1

19A116655P19

19A134202P6

19A700005P7

19A116655P7

19A700005P7

19A134202P6

19A700005P7

19A116656P10

19A700105P38

SYMBOL 19A700013P13 19A116655P7 C191 C192L С192Н 19A116656P18J C193L 19A116656P393 С193Н

C194L

C194H

C195H

C196

CR180

CR181

J101

L112

L113

L114

P902

Q102

Q103

Q104*

19A116656P12J8

19A116656P8J8

19A116656P6J

7489162P109

5495769P8

19A116052P2

19A701785P

19B219374G1

19A130255P3

19A130255P2

19A130443P1

19A130332P4

19A130443P2

19A130255P2

19A130443P1

19A130443P3

19B209420P10

19A700024P9

19B209420P

19A700024P9

19A116659P2

19A115910P1

19A702084P1

19A115328P1

19A116899P1

19A115328P1

DESCRIPTION GE PART NO. ramic disc: 1000 pF ±20%, 1000 VDCW; sim to Phenolic: 1.00 pF +5%, 500 VDCW. Ceramic disc: 150 pF ±20%, 1000 VDCW; sim to RMC Ceramic disc: 24 pF ±5%, 500 VDCW, temp coef -80

Ceramic disc: 18 pF ±5%, 500 VDCW, temp coef -80

Ceramic disc: 39 pF +5%, 500 VDCW, temp coef -

Ceramic disc: 27 pF $\pm 5\%$, 500 VDCW, temp coef -8

Ceramic disc: 12 pF ±5%, 500 VDCW; temp. coef -8

Ceramic disc: 8 pF ±5%, 500 VDCW; temp. coef -80

Ceramic disc: 9 pF ±5%, 500 VDCW; temp. coef -80

Ceramic disc: 6 pF $\pm 5\%$, 500 VDCW; temp. coef -80

- - - - - - DIODES AND RECTIFIERS - - - - -

Silicon, fast recovery; sim to Hewlett Packard

- - - - - - JACKS AND RECEPTACLES - - - - -

Connector, receptacle; 500 VDCW maximum; sim to NTTF-1058.

Contact, electrical; sim to Molex 08-50-0404.

- - - - - - - - INDUCTORS - - - - - -

Coil. RF: .15 uH +10%, .10 ohms DC res max; si

oil, RF: .10 uH $\pm 5\%$, .08 ohms DC res max; sim o Jeffers 4416-6J.

- - - - - - - - - PAUGS - - - - - - -

onnector, printed wiring: 10 contacts rated at

----- TRANSISTORS -----

Sprague Type 118. Added by REV A.

Silicon, capacitive

Connector: 9 contacts.

oil. RF: 470 nH +10%.

Coil, RF: 470 nH ±10%.

amps; sim to Molex 09-52-3102.

Silicon, NPN; sim to Type 2N3904

Silicon, NPN; sim to MPS 2369.

Silicon, NPN.

Silicon, NPN.

Silicon, NPN.

In REV C & earlier:

Coil.

DESCRIPTION SYMBOL | GE PART NO. 19A116201P3 Silicon NPN.

Silicon. PNP: sim to Type 2N3906,

Silicon, NPN; sim to Type 2N5210.

10%, 1/4 w; sim to CTS Type X-201

Composition: 5.1K ohms ±5%, 1/4 w.

Composition: 100K ohms +5%, 1/4 w,

Composition: 1K ohms +5%, 1/4 w

Composition: 1.5K ohms +5%, 1/4 w

Composition: 43K ohms ±5%, 1/4 w.

Composition: 8.2K ohms +5%, 1/4 w.

Composition: 470K ohms ±5%, 1/4 w.

Composition: 22K ohms ±5%, 1/4 w.

Composition: 1K ohms +5%, 1/4 w.

Composition: 180 ohms +5%, 1/4 w

Composition: 47K ohms +5%, 1/4 w.

Composition: 220 ohms $\pm 5\%$, 1/4 w.

Composition: 180 ohms ±5%, 1/4 w.

Composition: 150 ohms +10%, 1/4 w

Composition: 47K ohms +5%, 1/4 w.

Composition: 100 ohms +5%, 1/4 w.

Composition: 560 ohms +5%, 1/4 w.

Composition: 1K ohms ±5%, 1/4 w.

Composition: 68 ohms ±5%, 1/4 w.

Composition: 10 ohms +5%, 1/4 w.

Composition: 220 ohms +5%, 1/4 w.

Composition: 330 ohms ±5%, 1/4 w.

Composition: 1K ohms +5%, 1/4 w.

Composition: 47 ohms ±5%, 1/2 w.

Composition: 10 ohms ±5%, 1/4 w

Composition: 2.2K ohms +5%, 1/4 w.

Composition: 100 ohms ±5%, 1/4 w.

Composition: 180 ohms ±5%, 1/4 w.

Composition: 1K ohms ±5%, 1/4 w.

Composition: 10 ohms +5%, 1/4 w.

Composition: 47 ohms $\pm 5\%$, 1/4 w.

Composition: 27K ohms ±5%, 1/4 w.

Composition: 10K ohms ±5%, 1/4 w.

Composition: 1K ohms ±5%, 1/4 w.

Composition: 47 ohms +5%, 1/2 w

Allen-Bradley Type CB.

Composition: 10 ohms +5%, 1/4 w; sim to

Composition: 15 ohms $\pm 5\%$, 1/4 w; sim to Allen-Bradley Type CB.

llen-Bradley Type CB.

Composition: 22 ohms ±5%, 1/4 w; sim to

In REV B & earlier:

Composition: 47 ohms ±5%, 1/4 w.

Variable, carbon film: approx 300 to 10K ohms

Silicon, NPN.

Silicon, NPN.

In REV A & earlier:

19A116201P4

19A116201P1

19A700022P

19A116774P1

19A700106P53

19B209358P106

3R152P512J

19A700106P111

19A700106P63

19A700106P67

3R152P433J

19A700106P85

19A700106P31

19A700106P95

19A700106P63

19A700106P45

19A700106P103

19A700106P47

19A700106P45

3R152P151K

19A700106P103

9A700106P39

19A700106P57

9A700106P63

19A116310P39

9A700106P35

19A700106P15

94700106047

19A700106P51

L9A700106P63

9A116310P37

19A700113P31

9A700106P15

19A700106P71

19A116310P35

9A700106P45

9A700113P31

9A700106P63

9A700106P15

19A700106P31

19A700106P97

19A700106P87

9A700106P63

3R152P474J

Q182

R102

R105

R106

R108

R109

R110

R111

R112

R113

R115

R116

R118

R121*

R122

R123

R125

R126

R127

R128

R129

R131

R133

R134

R135

R136

R140

R141

R142

R144

R181

R182

R183

19A700106P57 R185 R187 R188 R189 R191 R192 ------ RESISTORS -----

RT182

T101

T102

T104

XY101*

Z101*

Z102*

SYMBOL

GE PART NO.

composition: 3.3K ohms ±5%, 1/4 w. 19A700106P75 19A701250P349 Metal film: 31.6K ohms +1%, 250 VDCW, 1/4 w. 19A701250P309 Metal film: 12.1K ohms ±1%, 250 VDCW, 1/4 w. 19A701250P287 Metal film: 7.87K ohms +1%, 250 VDCW, 1/4 w. 19A701250P283 Metal film: 7.15K ohms +1%, 250 VDCW, 1/4 w. 3R152P241J Composition: 240 ohms +5%, 1/4 w. 19A700106P105 Composition: 56K ohms ±5%, 1/4 w.

Composition: 560 ohms +5%, 1/4 w.

DESCRIPTION

19C300048P7 Thermister: 50K ohms $\pm 10\%$; sim to NL Industries 19C300048P15 Thermister: 200K ohms +10%; sim to NL Industries

19C307171P101 Paul Smith Co. Sample No. 080274-0G-1, 19C307170P305 Coil, RF; variable, wire size No. 20 AWG; sim. Paul Smith Co. Sample No. 092574-DS-2.

19C307170P306 Paul Smith Co. Sample No. 092574-DS-3. 19C307170P307 Coil, RF: variable, wire size No. 20 AWG; sim. Paul Smith Co. Sample No. 092574-DS-4. 19C307169P202 Coil. RF: variable, wire size No. 20 AWG: sim. Paul Smith Co. Sample No. 092574-DS-5.

19C307169P204 Coil. RF: variable, wire size No. 20 AWG: sim. and T108 Paul Smith Co. Sample No. 100374-DS-8. - - - - - - INTEGRATED CIRCUITS - - - - -Audio Amplifier

U101 19A702868G2 - - - - - - - VOLTAGE REGULATORS - - - - -VR101 4036887P9 Silicon, zener.

> 19A701785P1 Contact, electrical; sim to Molex 08-50-0404. 19C327251P1 Earlier than REV A: 19A116659P50

Connector, printed wiring: 6 contacts; sim to Molex 09-65-1061. - - - - - - - NETWORKS - - - - - -

Frequency network: selective, 460-600 MHz 19A134666P2 500 VDCW: sim to Dilectron TC501:NPO:270J:SLAC. Added by REV E. 19A134666P1 TC501:NPO:240J:SLAC. Added by REV E.

194701544P7 Can. (Used with T101-T108). 19C321695G1 19A701332P1 Insulator disk. (Used with Q105-Q107.

ASSOCIATED ASSEMBLIES

- - - - - - - CRYSTAL MODULES - - - - - -NOTE: When reordering, give GE Part Number and specify exact operating frequency needed

----- miscellaneous -----

¥101 Crystal module: 5 PPM, 406-420 MHz. 19B226962G6 19B226962G7 Crystal module: 5 PPM, 450-470 MHz 19B226962G8 Crystal module: 5 PPM, 470-494 MHz. 19B226962G9 Crystal module: 5 PPM, 494-512 MHz.

SYMBOL

GE PART NO.

DESCRIPTION

PRODUCTION CHANGES

Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter," which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for descriptions of parts affected by these revisions.

REV. A - To permit use with Custom MVP radios. Changed XY101 and

REV. B - To improve power output. Changed Q107.

REV. C - To improve power output at 512 MHz. Changed C156 and R121.

REV. D - To incorporate new transistor. Changed Q104.

REV. E - To incorporate new nomenclature for frequency networks.

PARTS LIST

406-512 MHz EXCITER 19D432582G1 406-450 MHz 19D432582G2 450-512 MHz ISSUE 2

SYMBOL	GE PART NO.	DESCRIPTION
C101	19A143481P19	Ceramic: 1000 pF ±20%, 1000 VDCW.
C103	19A701534P8	Tantalum: 0.47 uF ±20%, 35 VDCW.
C104	19A143486P7	Tantalum: 3.3 uF ±20%, 15 VDCW.
C104	19A143477P26	Polyester: .1 uF ±20%, 50 VDCW.
C108	19A143481P13	Ceramic: 470 pF ±20%, 1000 VDCW.
C109	19A143477P26	Polyester: .1 uF ±20%, 50 VDCW.
C111	19A143481P19	Ceramic: 1000 pF ±20%, 1000 VDCW.
C112	19A700105P44	Mica: 220 pF ±5%, 500 VDCW.
C113	5496372P365	Ceramic disc: 470 pF ±10%, 500 VDCW, temp coef -4700 PPM.
C114	19A701534P8	Tantalum: 0.47 uF ±20%, 35 VDCW.
C115	19A143481P13	Ceramic: 470 pF ±20%, 1000 VDCW.
C116	5496372P379	Ceramic disc: 910 pF \pm 10%, 500 VDCW, temp coef -4700 PPM.
C117	5496372P365	Ceramic disc: 470 pF \pm 10%, 500 VDCW, temp coef -4700 PPM.
C118L	19A143491P30J8	Ceramic: 30 pF ±5%, temp coef -80 PPM.
C118H	19A143491P27J8	Ceramic: 27 pF ±5%, temp coef -80 PPM.
C119	19A700013P15	Phenolic: 1.50 pF <u>+</u> 5%, 500 VDCW.
C121L	19A143491P30J8	Ceramic: 30 pF ±5%, temp coef -80 PPM.
C121H	19A143491P27J8	Ceramic: 27 pF ±5%, temp coef -80 PPM.
C122L	19A143491P24J8	Ceramic: 24 pF ±5%, temp coef -80 PPM.
C122H	19A143491P20J8	Ceramic: 20 pF ±5%, temp coef -80 PPM.
C124	19A700105P34	Mica: 100 pF ±5%, 500 VDCW.
C125	19A116655P21	Ceramic disc: 2700 pF $\pm 20\%$, 1000 VDCW; sim to RMC Type JF Discap.
C127 and C128	19A116655P21	Ceramic disc: 2700 pF $\pm 20\%$, 1000 VDCW; sim to RMC Type JF Discap.
C131	5491601P118	Phenolic: 0.75 pF ±5%, 500 VDCW.
C132	19A143481P19	Ceramic: 1000 pF ±20%, 1000 VDCW.
C133	19A143481P7	Ceramic: 150 pF ±20%, 1000 VDCW.
C134 thru C136	19A143481P19	Ceramic: 1000 pF ±20%, 1000 VDCW.
C136	19A700013P11	Phenolic: 0.68 pF +5%, 500 VDCW.
C138L	19A116656P56J8	Ceramic disc: 56 pF ±5%, 500 VDCW; temp coef -80 PPM.
C138H	19A143491P39J8	Ceramic: 39 pF ±5%, temp coef -80 PPM.
C139	19A143481P13	Ceramic: 470 pF ±20%, 1000 VDCW.
C141	19A143481P7	Ceramic: 150 pF ±20%, 1000 VDCW.
C143L	19A700105P26	Mica: 47 pF ±5%, 500 VDCW.
С143Н	19A700105P23	Mica: 39 pF ±5%, 500 VDCW.
C144	19A143477P21	Polyester: .047 uF ±20%, 50 VDCW.
C145L	19A143491P22J8	Ceramic: 22 pF ±5%, temp coef -80 PPM.
C145H	19A143491P15J8	Ceramic: 15 pP ±5%, temp coef -80 PPM.
C146	19A700013P10	Phenolic: 0.56 pF ±5%, 500 VDCW.
C147L	19A143491P30J8	Ceramic: 30 pF ±5%, temp coef -80 PPM.
C147H	19A143491P15J8	Ceramic: 15 pF ±5%, temp coef -80 PPM.
C148	19A143491P30J8	Ceramic: 30 pF ±5%, temp coef -80 PPM.
C149	19A143481P7	Ceramic: 150 pF <u>+</u> 20%, 1000 VDCW.
	ı	

C151 C15LL C152H	19A143481P7	Ceramic: 150 pF ±20%, 1000 VDCW.		L
	ı	•	L105	19
C152H	19A143491P4J0	Ceramic: 4 pF ±5%, temp coef 0 PPM.	L105	19,
	19A143491P3J0	Ceramic: 3 pF ±5%, temp coef 0 PPM.	L106L L106H	
C154	19A143481P19	Ceramic: 1000 pF ±20%, 1000 VDCW.		19
C155	19A700008P1	Variable: 2.04 to 9.9 pF, 250V peak.	L107	19,
C156	19A700013P14	Phenolic: 1.20 pF ±5%, 500 VDCW.	L108	19,
C157	19A700008P1	Variable: 2.04 to 9.9 pF, 250V peak.	L109	19
C161L	19A143491P6J8	Ceramic: 6 pF ±5%, temp coef -80 PPM.	L111	191
C161H	19A143491P5J8	Ceramic: 5 pF ±5%, temp coef -80 PPM.	L112	19,
C162	19A143491P47J1	Ceramic: 47 pF ±5%, temp coef -150 PPM.	L113	191
C163	19A143491P30J8	Ceramic: 30 pF ±5%, temp coef -80 PPM.		
C164	19A143481P7	Ceramic: 150 pF ±20%, 1000 VDCW.	L114	19
C166L	19A143491P4J0	Ceramic: 4 pF ±5%, temp coef 0 PPM.	Į.	
С166Н	19A143491P3J0	Ceramic: 3 pF ±5%, temp coef 0 PPM.	P902	19
C167	19A700008P1	Variable: 2.04 to 9.9 pF, 250V peak.	1	
C168	19A143491P47J1	Ceramic: 47 pF +5%, temp coef -150 PPM	ļ	
C171	19A700008P1	Variable: 2.04 to 9.9 pF, 250V peak.	Q101	19.
C172	19A143477P26	Polyester: .1 uF ±20%, 50 VDCW.	Q102	19,
C175	19A700008P1	Variable: 2.04 to 9.9 pF, 250V peak.	Q103	19
C176	19A143481P19	Ceramic: 1000 pF ±20%, 1000 VDCW.	Q103 Q104	19
C177	19A701534P8	Tantalum: 0.47 uF ±20%, 35 VDCW.	Q104 Q105	19
C177	19A143477P13	<u>-</u>	and Q106	191
		Polyester: .01 uF ±20%, 50 VDCW.	,	197
C179	19A143481P7	Ceramic: 150 pF ±20%, 1000 VDCW.	Q107	İ
C180	19A143477P13	Polyester: .01 uF +20%, 50 VDCW.	Q181	197
C181 and C182	19A701534P8	Tantalum: 0.47 uF ±20%, 35 VDCW.	Q182	19/
C183	19A143477P13	Polyester: .01 uF ±20%, 50 VDCW.	R102	197
C184	19A143491P100J7	Ceramic: 100 pF ±5%, temp coef -750 PPM.	R104	191
C185	19A700105P38	Mica: 150 pF ±5%, 500 VDCW.	""	101
C186 thru	19A143481P19	Ceramic: 1000 pF ±20%, 1000 VDCW.	R105	3R:
C189			R106	19
C190	19A700013P13	Phenolic: 1.00 pF <u>+</u> 5%, 500 VDCW.	R107	19
C191	19A143481P7	Ceramic: 150 pF <u>+</u> 20%, 1000 VDCW.	R108	197
C192L	19A143491P24J8	Ceramic: 24 pF ±5%, temp coef -80 PPM.	R109	3R
С192Н	19A143491P18J8	Ceramic: 18 pF ±5%, temp coef -80 PPM.	R110	197
C193L	19A143491P39J8	Ceramic: 39 pF ±5%, temp coef -80 PPM.	R111	19/
:193н	19A143491P27J8	Ceramic: 27 pF ±5%, temp coef -80 PPM.	R112	3R1
194L	19A143491P12J8	Ceramic: 12 pF ±5%, temp coef -80 PPM.	R113	19/
:194н	19A143491P8J8	Ceramic: 8 pF ±5%, temp coef -80 PPM.	and R114	
195L	19A143491P9J8	Ceramic: 9 pF ±5%, temp coef -80 PPM.	R115	19/
:195н	19A143491P6J8	Ceramic: 6 pF ±5%, temp coef -80 PPM.	R116	19
C196	7489162P109	Silver mica: 18 pF ±10%, 500 VDCW; sim to	R117	19
		Sprague Type 118.	R118	19
			R121	19/
CR180	5495769P8	Silicon, capacitive.	R122	19/
CR181	19A116052P2	Silicon, fast recovery; sim to Hewlett Packard	R123	19/
	i	5082-2811.	R125	19/
			R126	19/
J101	19A700049P2	Connector, receptacle: 500 VDCW maximum; sim to NTTF-1058.	R127	19/
J102	19A701785P1	Contact, electrical; sim to Molex 08-50-0404. (Quantity 2).	R128	19/
J103	19B219374G1	Connector, Includes: Shell.	R129	194
			R131	194
	- 1		R132	19/
L101	19A130255P3	Coil.	R133	19/
L104	19A130255P2	Coil.	R134	19/

		SYMBOL	GE PART NO.	DESCRIPTION
		L105	19A130443P1	Coil.
		L106L	19A130443P4	Coil.
		L106H	19A130443P2	Coil.
		L107	19A130255P2	Coil.
		L108	19A130443P1	Coil.
		L109	19A130443P3	Coil.
		L111	19B209420P103	Coil, RF: .15 uH ±10%, .10 ohms DC res max; sim to Jeffers 4416-3K.
		L112	19A700024P9	Coil, RF: 470 nH ±10%.
		L113	19B209420P1	Coil, RF: .10 uH $\pm 5\%$, .08 ohms DC res max; sim to Jeffers 4416-6J.
		L114	19A700024P9	Coil, RF: 470 nH ±10%.
		P902	19A116659P2	Connector, printed wiring: 10 contacts rated at 5 amps; sim to Molex 09-52-3102.
				TRANSISTORS
		Q101	19A115910P1	Silicon, NPN; sim to Type 2N3904.
		Q102	19A702084P1	Silicon, NPN; sim to MPS 2369.
		Q103	19A115328P1	Silicon, NPN.
		Q104	19A116899P1	Silicon, NPN. Silicon, NPN.
		Q105 and Q106	19A116201P3	SALICUR, NEW.
1		Q107	19A116201P4	Silicon, NPN.
		Q181	19A700022P1	Silicon, PNP; sim to Type 2N3906.
		Q182	19A116774P1	Silicon, NPN; sim to Type 2N5210.
		R102	19A700106P53	Composition: 390 ohms ±5%, 1/4 w.
		R104	19B209358P106	Variable, carbon film: approx 300 to 10K ohms ±10%, 1/4 w; sim to CTS Type X-201.
ı		R105	3R152P512J	Composition: 5.1K ohms $\pm 5\%$, 1/4 w.
		R106	19A700106P111	Composition: 100K ohms ±5%, 1/4 w.
		R107	19A700106P63	Composition: 1K ohms $\pm 5\%$, 1/4 w.
		R108	19A700106P67	Composition: 1.5K ohms ±5%, 1/4 w.
-		R109	3R152P433J	Composition: 43K ohms ±5%, 1/4 w.
		R110	19A700106P85	Composition: 8.2K ohms ±5%, 1/4 w.
	ļ	R111	19A700106P31	Composition: 47 ohms ±5%, 1/4 w.
		R112	3R152P474J 19A700106P95	Composition: 470K ohms ±5%, 1/4 w.
		R113 and R114	194700106P95	Composition: 22K ohms ±5%, 1/4 w.
	Н	R115	19A700106P63	Composition: 1K ohms ±5%, 1/4 w.
		R116	19A700106P45	Composition: 180 ohms $\pm 5\%$, 1/4 w.
		R117	19A700106P103	Composition: 47K ohms ±5%, 1/4 w.
- [R118	19A700106P47	Composition: 220 ohms ±5%, 1/4 w.
		R121	19A700106P45	Composition: 180 ohms ±5%, 1/4 w.
		R122	19A700106P103	Composition: 47K ohms ±5%, 1/4 w.
ļ		R123	19A700106P39	Composition: 100 ohms ±5%, 1/4 w.
$\lfloor \rfloor$		R125	19A700106P57	Composition: 1K object +5%, 1/4 w.
		R126 R127	19A700106P63 19A116310P39	Composition: 1K ohms $\pm 5\%$, $1/4$ w. Composition: 22 ohms $\pm 5\%$, $1/4$ w; sim to
				Allen-Bradley Type CB.
		R128	19A700106P35	Composition: 68 ohms ±5%, 1/4 w.
-		R129	19A700106P15	Composition: 220 ohms ±5%, 1/4 w.
_		R131	19A700106P47	Composition: 220 ohms ±5%, 1/4 w.
		R132 R133	19A700106P51 19A700106P63	Composition: 330 ohms ±5%, 1/4 w. Composition: 1K ohms ±5%, 1/4 w.
	1	R134	19A116310P37	Composition: 15 ohms ±5%, 1/4 w. Composition: 15 ohms ±5%, 1/4 w; sim to
		RT0.4	101110010101	Allen-Bradley Type CB.

LBI30060

	GE PART NO.	DESCRIPTION	SYMBOL	GE PART NO
R135	19A700113P31	Composition: 47 ohms <u>+</u> 5%, 1/2 w.		
R136	19A700106P15	Composition: 10 ohms ±5%, 1/4 w.		!
R137	19 A 700106P71	Composition: 2.2K ohms ±5%, 1/4 w.		19C321695G1
R138	19A700106P39	Composition: 100 ohms ±5%, 1/4 w.		19A701544P7
R139	19A116310P35	Composition: 10 ohms ±5%, 1/4 w; sim to Allen-Bradley Type CB.		19C327251P1 19A701332P1
R140	19A700106P45	Composition: 180 ohms ±5%, 1/4 w.		
R141	19A700113P31	Composition: 47 ohms ±5%, 1/2 w.		
R142	19A700106P63	Composition: 1K ohms ±5%, 1/4 w.		
R144	19A700106P15	Composition: 10 ohms ±5%, 1/4 w.		
R181	19A700106P31	Composition: 47 ohms ±5%, 1/4 w.		
R182	19A700106P97	Composition: 7K ohms ±5%, 1/4 w.		
R183 R184	19A700106P87	Composition: 10K ohms ±5%, 1/4 w.		
R185	19A700106P63 19A700106P57	Composition: 1K ohms ±5%, 1/4 w. Composition: 560 ohms ±5%, 1/4 w.	Y101	19A701562G6
R186	19A700106P75	Composition: 3.3K ohms ±5%, 1/4 w.		
R187	19A701250P349	Metal film: 31.6K ohms ±1%, 250 VDCW, 1/4 w.		
R188	19A701250P308	Metal film: 11.8K ohms +1%, 250 VDCW, 1/4 w.		
R189	19A701250P287	Metal film: 7.87K ohms ±1%, 250 VDCW, 1/4 w.		
R190	19A701250P283	Metal film: 7.15K ohms ±1%, 250 VDCW, 1/4 w.		
R191	3R152P241J	Composition: 240 ohms ±5%, 1/4 w.		
R192	19A700106P105	Composition: 56K ohms ±5%, 1/4 w.		
RT181	19C300048P7	Thermister: 50K ohms ±10%; sim to NL Industries iD103.		
T182	19C300048P15	Thermister: 200K ohms $\pm 10\%$; sim to NL Industries 4D0514.		
.01	19C307171P101	Coil, RF: variable, wire size No. 34 AWG; sim to Paul Smith Co. Sample No. 080274-0G-1, 092574-DS-1.		
102	19C307170P305	Coil, RF: variable, wire size No. 20 AWG; sim to Paul Smith Co. Sample No. 092574-DS-2.		
.03	19C307170P306	Coil, RF: variable, wire size No. 20 AWG; sim to Paul Smith Co. Sample No. 092574-DS-3.		
104	19C307170P307	Coil, RF: variable, wire size No. 20 AWG; sim to Paul Smith Co. Sample No. 092574-DS-4.		
105	19C307169P202	Coil, RF: variable, wire size No. 20 AWG; sim to Paul Smith Co. Sample No. 092574-DS-5.		
106	19C3O7169P2O3	Coil, RF: variable, wire size No. 20 AWG; sim to Paul Smith Co. Sample No. 092574-DS-6.		
107 nd	19C307169P204	Coil, RF: variable, wire size No. 20 AWG; sim to Paul Smith Co. Sample No. 100374-DS-8.		
108		INTEGRATED CIRCUITS		
101	19A702868G2	Audio Amplifier.		
'R101	4036887P9	Silicon, zener.		
Y101	19A701785P1	Contact, electrical; sim to Molex 08-50-0404. (Quantity 6).		
101	19A134666P2	Frequency network: 460-600 MHz resonant freq 500 VDCW, sim to Dilectron TC501:NPO:270J:SLAC.		
102	19A134666P1	Frequence network: selective, 470-630 MHz, resonant freq 500 VDCW; sim to Dilectron		
		TC501:NPO:240J:SLAC.		

SYMBOL	GE PART NO.	DESCRIPTION	
	19C321695G1 19A701544P7 19C327251P1 19A701332P1	MISCELLANEOUS Shield. Can. Cleat. (Secures XY101). Insulator disk. (Used with Q105-Q107). ASSOCIATED PARTS	
	:	NOTE: When reordering, give GE Part Number and specify exact frequency needed. Fx = $\frac{Fo}{9}$	
Y101	19A701562G6	Quartz: 31-66 MHz.	
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